

LEOCO CORPORATION	PRODUCTION SPECIFICATION	No.	S-01-1262-3
-------------------	--------------------------	-----	-------------

* 1.25mm(.049")pitch Wire to Board connector system *

This product specification contains the test method, the general performance and requirement for LEOCO 1262 and 1263 series, receptacle housing, terminal, (SMT)straight pin header, (SMT)right angle pin header.

1. Construction and dimensions shall be in accordance with the referenced drawings.
2. 产品结构和尺寸依据所提的产品图面
3. Characteristics 特性:
 Current rating 额定电流: 1 Amp.
 Voltage rating 额定电压: AC 125 Volts.
 Temperature rating 额定温度: -40°C to +85°C.

4. Electrical performance 电气特性:

ITEM 项目	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法及条件	REQUIREMENT 要求
3-1	Contact Resistance 接触阻抗	It should be tested in accordance with method 3004.1 of MIL-STD-1344A.	20MΩ max.
3-2	Insulation Resistance 绝缘电阻	It should be tested in accordance with method 3003.1 of MIL-STD-1344A.	100MΩ min.
3-3	Dielectric Withstanding Voltage 耐电压	Unmated connector shall be tested in accordance with method 3003.1 of MIL-STD-1344A. When the AC 500V rms for one minute applied between adjacent contacts.	No evidence of break down and flash over.

4. Mechanical Performance 机械特性 :

ITEM 项目	DESCRIPTION 内容	TEST METHOD & CONDITION 测试方法及条件	REQUIREMENT 要求
4-1	Post Retention Force 保持力	At a constant speed of 25mm/minute.	454 gram min.
4-2	Durability 耐久力	It should be tested in accordance with method 2016 of MIL-STD-1344A. Connector shall be subjected to 30 cycles of insertion and withdrawal.	No defect.

LEOCO CORPORATION	PRODUCTION SPECIFICATION	No.	S-01-1262-3
-------------------	--------------------------	-----	-------------

5.Environmental Performance 环境特性:

Item 项目	Description 内容	Test Method & Condition 测试方法及条件	Requirement 要求
5-1	Salt Spray 盐雾测试	Connector shall be tested in accordance with method 100.1 of MIL-STD-1344A condition B. Temperature:35±2℃ Density: 5% in weight Period:48 hours.	No damage. Contact resistance less than twice of initial.
5-2	Solderability 着锡性	Connector termination ends shall be checked for solder ability in accordance with method 208 of MIL-STD-202F. Solder temperature:245±5℃ Immersion period:5±0.5sec	No damage. Minimum:90% of immersed area.
5-3	Resistance to Soldering Heat 耐高温焊接	Specimen shall be mounted on PCB. Solder temperature:260±5℃ Immersion period:10±0.5sec	No damage and deformation .

APPROVED BY:	CHECKED BY:	SPEC BY:
--------------	-------------	----------